

Product Change Notice (PCN)

Subject: Alternate assembly facility of the listed Renesas TQFN packaged products

Publication Date: 6/18/2025

Effective Date: 9/16/2025

Revision Description:

Initial Release

Description of Change:

Alternate assembly facility of the listed Renesas DFN, QFN, TQFN packaged products

- *Advanced Semiconductor Engineering, Chung Li, Taiwan ROC (ASECL)*

Affected Devices:

RAA489108A3GNP#AAO	RAA489300ARGNP#AAO	RAA4893013SOJGNP#HAO	RAA489301AS08GNP#HAO
RAA489108A3GNP#HAO	RAA489300ARGNP#HAO	RAA489301A3GNP#AAO	RAA489301AS0HGNP#HAO
RAA489108ARGNP#AAO	RAA489300AS07GNP#HAO	RAA489301A3GNP#HAO	RAA489301AS0NGNP#HAO
RAA489108ARGNP#HAO	RAA489300AS08GNP#HAO	RAA489301ARGNP#AAO	< Blank >
RAA489108AS08GNP#HAO	RAA489300AS0HGNP#HAO	RAA489301ARGNP#HAO	< Blank >
RAA489108AS0JGNP#HAO	RAA4893013S08GNP#HAO	RAA489301AS07GNP#HAO	< Blank >

This notice is to inform you that Renesas will begin using ASE, Chung Li (ASECL) facility as alternate assembly facility of the Listed Renesas TQFN (Thin Quad Flat No Leads) packaged products.

Reason for Change:

The ASECL facility is ISO9001:2015 and IATF 16949:2016 certified. ASECL is currently an existing assembly supplier to Renesas for high volume assembly of TQFN packaged products. This action will expand current capabilities and capacities to optimize Renesas's ability to meet customer's delivery requirements.

Impact on fit, form, function, quality & reliability:

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function or interchangeability of the product. A summary of the qualification result is included for reference. Please refer Appendix A. The remainder of the manufacturing operations (wafer fabrication, package level electrical test, etc) will continue to be processed to previously established manufacturing flow.

Product Identification:

Products affected by this change are identifiable via Renesas's internal traceability system. In addition, Copper product may also be identified by the assembly site code which marked on the devices. The site code for product assembled at ASECL is "W" for Copper (Cu) wire products.

#	Assembly Site	Site Code	Remarks
1	ASECL	W	For Copper wire products

Qualification status: Completed, See attached
Sample availability: 8/1/2025
Device material declaration: Available upon request

Sample is available Aug 01, 2025 onwards, and subject to availability. Customer may expect 1 – 2 months for sample replenishment.


Note:


1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@RENESAS.COM	Europe: PCN-EU@RENESAS.COM	Japan: PCN-JP@RENESAS.COM	Asia Pac: PCN-APAC@RENESAS.COM

Appendix A : ASECL Qualification result

Test Description	Condition	ISL85415AIRZ 12 LEAD, 4.0mm X 3.0mm DFN Package	ISL95855AHRTZ-T 48 LEAD, 6.0 X 6.0 TQFN Package
Moisture Sensitivity Classification		N = 1753 Acc = 0 L3 Pb Free	N = 1120 Acc = 0 L3 Pb Free
High Temperature Operating Life +125 °C	1000 hrs	N = 80 Acc = 0	N = 157 Acc = 0
Temperature/Humidity/Bias +85 °C / 85% RH	1000 hrs	N = 80 Acc = 0	N = 80 Acc = 0
Biased HAST +130 °C / 85% RH	96 Hrs	N = 239 Acc = 0	
Unbiased HAST (u-HAST) +130 °C / 85% RH	96 Hrs	N = 78 Acc = 0	N = 636 Acc = 0
Hot Temperature Storage (HTS) +150 °C	1000 Hrs	N = 162 Acc = 0	
Temperature Cycle (TCT) -40 °C / +125 °C	1000 cyc	N = 322 Acc = 0	N = 636 Acc = 0

 Qualified by Extension

 Not Applicable (NA)